



Material Content Data Sheet



Sales Product Name	TLD7306EK			Issued		28. August 2013		
MA#	MA000969182							
Package	PG-DSO-14-43			Weight*		149.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.255	2.84	2.84	28443	28443
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		465	
	non noble metal	iron	7439-89-6	1.392	0.93		9304	
	non noble metal	copper	7440-50-8	56.512	37.78	38.77	377792	387677
wire	non noble metal	copper	7440-50-8	0.379	0.25	0.25	2537	2537
encapsulation	organic material	carbon black	1333-86-4	0.166	0.11		1111	
	plastics	epoxy resin	-	7.647	5.11		51125	
	inorganic material	silicondioxide	60676-86-0	75.311	50.35	55.57	503466	555702
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8197	8197
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9476	9476
glue	plastics	epoxy resin	-	0.298	0.20		1992	
	noble metal	silver	7440-22-4	0.894	0.60	0.80	5976	7968
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com